

"Economic driving force of 3D systems vs. Moore's law"

Daniel Gitlin

Abstract:

A standard cost model used in the Industry is extended to 3D systems. Examples of applications of this model will be provided and contrasted against Moore's law. Both monolithic technology migrations and new integration technologies balance manufacturing complexity vs. footprint reduction. The net result can only be quantified with adequate models that illustrate the trade-offs and help extract adequate technology targets and applicability range. The talk will cover Moore's law, Chip-on-wafer as well as monolithic 3D technologies.

Biography



Daniel Gitlin, is currently with Broadcom Limited, in charge of the silicon supply business. He was formerly an independent consultant and Scientific Advisor to CEA-Let. He served as Sr. Vice President, Manufacturing and Product Technology at Tabula Inc. where he lead silicon and packaging technology as well as product and test Engineering, Q&R and manufacturing operations.

Prior to joining Tabula, Daniel was Vice President of Semiconductor Technology at Xilinx. Daniel was instrumental in driving process technology and establishing key industry partnerships during his 15 year tenure. Before Xilinx, Daniel was a member of the technical staff at LSI Logic Corporation.

With more than 25 years of experience in semiconductors and business, Daniel has served as a member of the Technology Strategy Committee of the Semiconductor Industry Association (SIA), has published numerous technical publications and holds eighteen patents.

Daniel received his bachelor's degree in engineering physics from the UAM, Mexico and graduate degrees in applied physics and electrical engineering from Harvard University and UCLA, respectively.